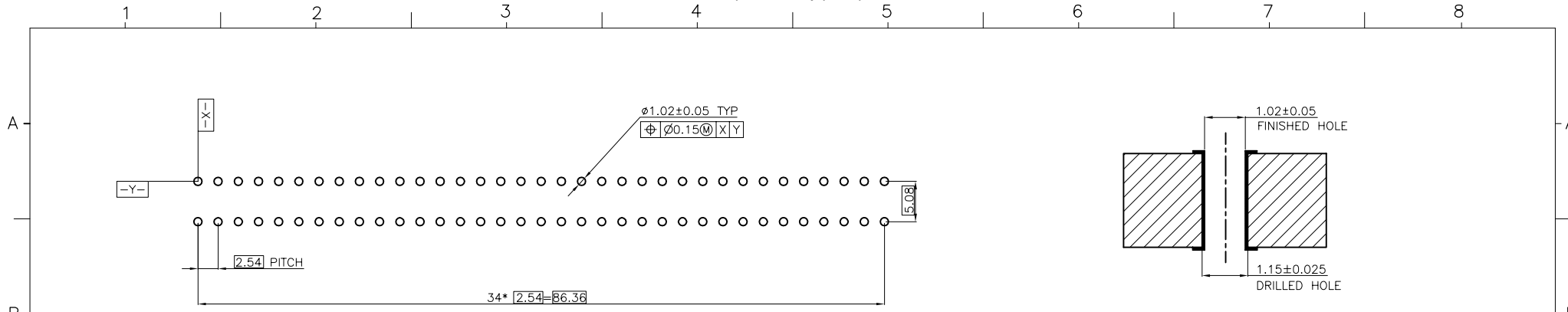


**NOTE:**

- MATERIAL:**  
HOUSING-THERMAL PLASTIC UL94V-0,COLOR:BLACK.  
CONTACTS:PHOSPHOR BRONZE.
- CONTACT PLATING:**  
ALL AREA UNDERPLATED 50~100u"NICHEL  
30u" GOLD ON THE CONTACT AREA,  
40~80u"MATTE TIN ON THE PRESS-FIT AREA.
- RECOMMENDED PCB FINISHED HOLE DIA:1.02±0.05mm.**  
THE PC BOARD THICKNESS: 2.0MM MIN.
- CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.
- ROHS DIRECTIVE COMPLIANCE.
- CHARACTERISTICS**  
1>CURRENT RATING: 3A MAX PER CONTACT FOR UL  
2>.DIELECTRIC WITHSTANDING VOLTAGE: 1000V AC/MINUTE  
3>.CONTACT RESISTANCE: 30mΩ max.  
4>.INSULATION RESISTANCE: 5000 MΩ min.
- MECHANICAL**  
1>.DURABILITY: 200 CYCLES.  
2>.OPERATION TEMPERATURE: -55°C ~ +85°C

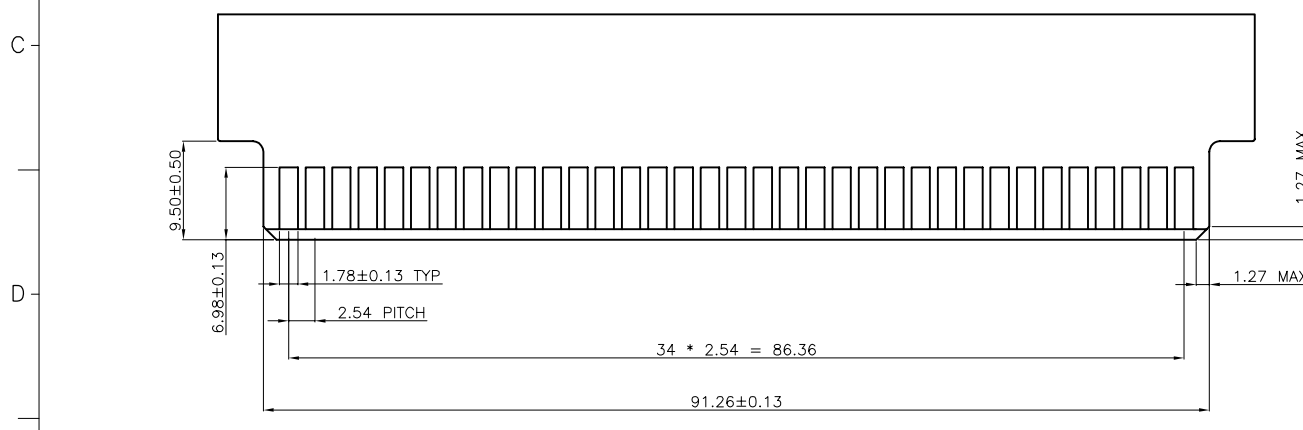
UNITS ■ mm □ INCH		NAME: POWER EDGE CONNECTOR TYPE II 35Pos. PRESS-FIT		 NEXTRONICS ENGINEERING CORP.	
GENERAL TOLERANCES: (UNLESS SPECIFIED)		PART NO: R-825F113135000		TITLE: CUSTOMER DWG.	
		APPD: Seawen 10/10,12		DWG NO: 010-0000-804	
		CHKD: Annie 10/10,12		SCALE: SHEET: REV.: 2:1 1/2 A	
		DRAWN: Jone 10/10,12			

REV.	DESCRIPTION	DATE	APPD
A	ECN-210201	10/25,12	Seawen
X3	PITCH公差設變 X3=1	2/28,12	Seawen
X2	設計變更 X2=3	6/14,11	Seawen

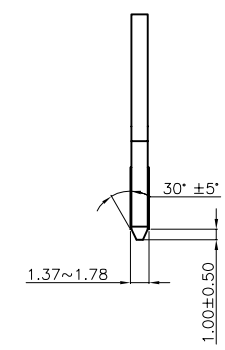


THE PC BOARD LAYOUT  
(PC BOARD THICKNESS: 2.0MM MIN.)

RECOMMENDED TIN PLATED THROUGH HOLE DIMENSIONS  
COPPER PLATE THICKNESS: 0.03MM (PER SURFACE)  
TIN PLATE THICKNESS: 0.008MM (PER SURFACE)



DAUGHTER CARD LAYOUT



UNITS ■ mm □ INCH		NAME: POWER EDGE CONNECTOR TYPE II 35Pos. PRESS-FIT		NEXTRONICS ENGINEERING CORP.	
GENERAL TOLERANCES: (UNLESS SPECIFIED)		PART NO: R-825F113135000		TITLE: CUSTOMER DWG.	
		APPD: Seawen 10/10,12		DWG NO: 010-0000-804	
		CHKD: Annie 10/10,12		SCALE: SHEET: REV.: 2:1 2/2 A	
		DRAWN: Jone 10/10,12			

REV.	DESCRIPTION	DATE	APPD
A	ECN-210201	10/10,12	Seawen
X3	PITCH公差變更 X3=1	2/28,12	Seawen
X2	設計變更 X2=3	6/14,11	Seawen